



Pentium®/II Clock Synthesizer/Driver for Desktop PCs with Intel 82440LX and 3–4 DIMMs

Features

- Mixed 2.5V and 3.3V operation
- Single-chip clock solution to meet requirements of Pentium® and Pentium® II motherboards
 - Multiple CPU clocks at 2.5V supporting single and dual-processor systems
 - Seven synchronous PCI clocks
 - Multiple 2.5V IOAPIC clocks at 14.318 MHz
 - Multiple 3.3V SDRAM clocks
 - Multiple 3.3V USB and I/O clocks
 - Multiple 3.3V Ref. clocks at 14.318 MHz
- I²C™ Serial Configuration Interface
- Factory-EPROM programmable output drive and slew rate for EMI customization
- Factory-EPROM programmable clock frequencies for custom configurations
- High drive, low skew, and low jitter outputs
- Available in space-saving 56-pin SSOP package

Functional Description

The CY2276A-21 and CY2276A-31 are single-chip clock generators for Pentium or Pentium II systems designed with the Intel® 82440LX or similar chipset. They differ in the number of

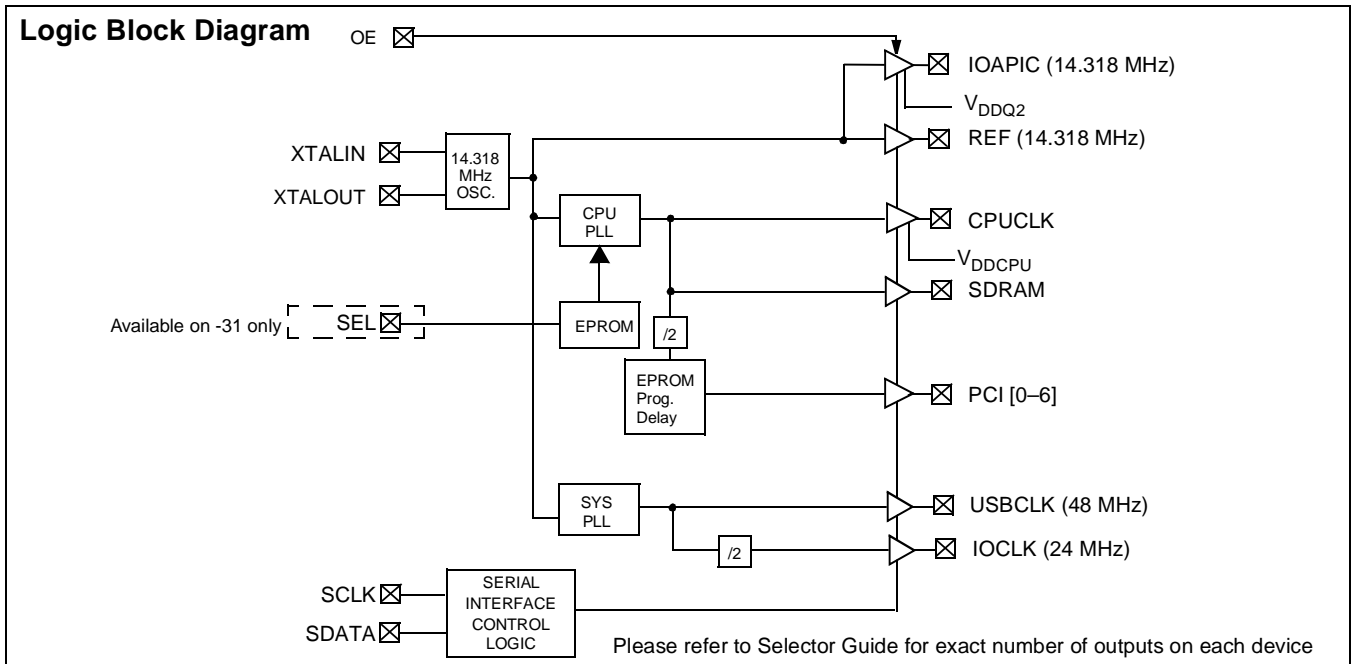
outputs available from each device, as shown in the Selector Guide.

The CY2276A-21 is ideal for four-SDRAM module or server applications that require sixteen SDRAM clocks, and do not require the ability to stop CPU clocks. The CY2276A-31 is ideal for single-processor or dual-processor desktop systems, which require an extra CPU clock.

All CY2276A outputs are designed for low EMI emissions. Controlled rise and fall times, unique output driver circuits and factory-EPROM programmable output drive and slew-rate enable optimal configurations for EMI control.

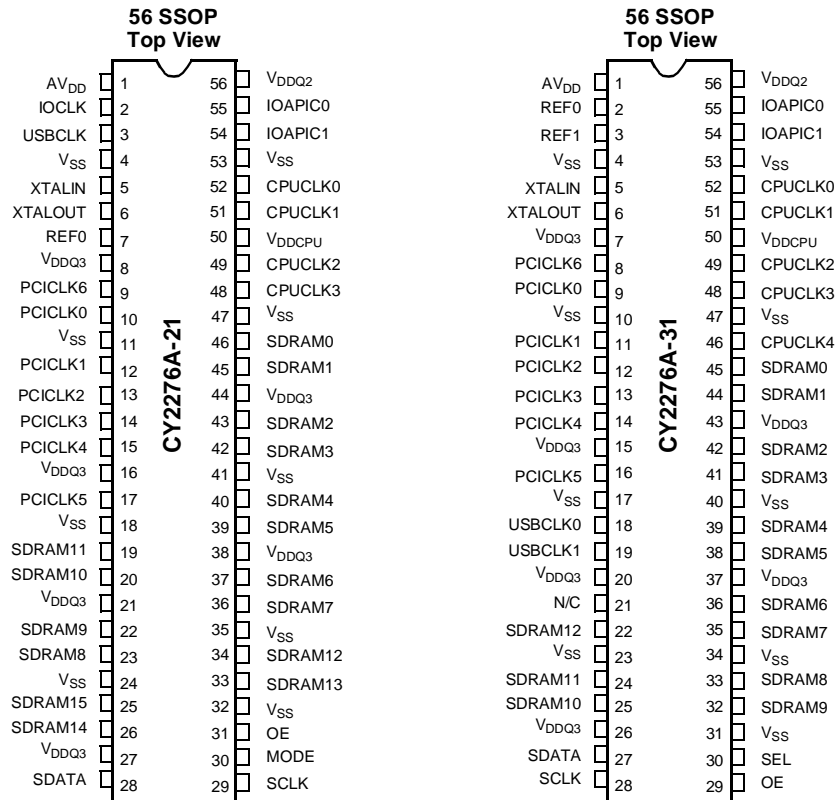
CY2276A Selector Guide.

Clock Outputs	-21	-31
CPU (60, 66.6 MHz)	4	5
SDRAM	16	13
PCI (CPU/2 MHz)	7	7
IOAPIC (14.318 MHz)	2	2
USB/IO (48 MHz)	1	2
IO (24 MHz)	1	0
Ref. (14.318 MHz)	1	2
CPU-PCI delay	1–6 ns	1–5 ns



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Pin Configurations



Pin Summary

Name	Pins (-21)	Pins (-31)	Description
V _{DDQ3}	8, 16, 21, 27, 38, 44	7, 15, 20, 26, 37, 43	3.3V Digital voltage supply
V _{DDQ2}	56	56	IOAPIC Digital voltage supply, 2.5V
V _{DDCPU}	50	50	CPU Digital voltage supply, 2.5V
AV _{DD}	1	1	Analog voltage supply, 3.3V
V _{SS}	4, 11, 18, 24, 32, 35, 41, 47, 53	4, 10, 17, 23, 31, 34, 40, 47, 53	Ground
XTALIN ^[1]	5	5	Reference crystal input
XTALOUT ^[1]	6	6	Reference crystal feedback
SDRAM[0–15] (-21) SDRAM[0–12] (-31)	46, 45, 43, 42, 40, 39, 37, 36, 23, 22, 20, 19, 34, 33, 26, 25	45, 44, 42, 41, 39, 38, 36, 35, 33, 32, 25, 24, 22	SDRAM clock outputs
OE	31	29	Active HIGH output enable, disables all outputs when asserted
CPUCLK [0–3] (-21) CPUCLK [0–4] (-31)	52, 51, 49, 48	52, 51, 49, 48, 46	CPU clock outputs
PCICLK [0–6] (A//)	10, 12, 13, 14, 15, 17, 9	9, 11, 12, 13, 14, 16, 8	PCI clock outputs, running at one-half the CPU frequency
IOAPIC [0–1] (A//)	55, 54	55, 54	IOAPIC clock outputs
REF0 (-21) REF [0–1] (-31)	7	2, 3	Reference clock outputs, 14.318 MHz. REF0 drives 45 pF load
USBCLK (-21) USBCLK [0–1] (-31)	3	18, 19	48 MHz USB clock output
IOCLK	2	N/A	24 MHz I/O clock output
SDATA	28	27	Serial data input for serial configuration port
SCLK	29	28	Serial clock input for serial configuration port
CPU_STOP	N/A	N/A	Active LOW input, disables CPU clocks when asserted
MODE	30	N/A	Mode input, not used, tie to V _{SS}
N/C	N/A	21	Not connected. Tie to V _{SS}
SEL	N/A	30	CPU frequency select input (see Function Table)

Note:

- For best accuracy, use a parallel-resonant crystal, C_{LOAD} = 18 pF.

Function Table

Device	OE	SEL	XTALIN	CPUCLK SDRAM	PCICLK	REF IOAPIC	USB	I/O (-21 only)
-21	0	N/A	14.318 MHz	Hi-Z	Hi-Z	Hi-Z	Hi-Z	Hi-Z
-21	1	N/A	14.318 MHz	66.67 MHz	33.33 MHz	14.318 MHz	48 MHz	24 MHz
-31	0	X	14.318 MHz	Hi-Z	Hi-Z	Hi-Z	Hi-Z	N/A
-31	1	0	14.318 MHz	60 MHz	30 MHz	14.318 MHz	48 MHz	N/A
-31	1	1	14.318 MHz	66.67 MHz	33.33 MHz	14.318 MHz	48 MHz	N/A

Actual Clock Frequency Values

Clock Output	Target Frequency (MHz)	Actual Frequency (MHz)	PPM
CPUCLK	66.67	66.654	-195
CPUCLK	60.0	60.0	0

CPU and PCI Clock Driver Strengths

- Matched impedances on both rising and falling edges on the output drivers
- Output impedance: 25Ω (typical) measured at 1.5V.

Byte 0: Functional and Frequency Select Clock Register (1 = Enable, 0 = Disable)

Bit	Pin #	Description	
Bit 7	--	(Reserved) drive to '0'	
Bit 6	--	(Reserved) drive to '0'	
Bit 5	--	(Reserved) drive to '0'	
Bit 4	--	(Reserved) drive to '0'	
Bit 3	--	(Reserved) drive to '0'	
Bit 2	--	(Reserved) drive to '0'	
Bit 1	--	Bit 1	Bit 0
Bit 0	--	1	1 - N/A
		1	0 - N/A
		0	1 - Testmode
		0	0 - Normal Operation

Serial Configuration Map

- The Serial bits will be read by the clock driver in the following order:
 - Byte 0 - Bits 7, 6, 5, 4, 3, 2, 1, 0
 - Byte 1 - Bits 7, 6, 5, 4, 3, 2, 1, 0
 - ...
 - Byte N - Bits 7, 6, 5, 4, 3, 2, 1, 0
- Reserved and unused bits should be programmed to "0".
- I²C Address for the CY2276A-21,-31 is:

A6	A5	A4	A3	A2	A1	A0	R/W
1	1	0	1	0	0	1	----

Select Functions

Functional Description	Outputs				
	CPU	PCI, PCI_F	SDRAM	Ref	IOAPIC
Test Mode	TCLK/2 ^[2]	TCLK/4	TCLK/2	TCLK	TCLK

Note:

2. TCLK supplied on the XTALIN pin in Test Mode.

Byte 1: CPU Active/Inactive Register
(1 = Active, 0 = Inactive), Default = Active

Bit	Description
Bit 7	IOCLK (Active/Inactive) (-21 ONLY) USBCLK0 (Active/Inactive) (-31 ONLY)
Bit 6	USBCLK (Active/Inactive) (-21 ONLY) USBCLK1 (Active/Inactive) (-31 ONLY)
Bit 5	(Reserved) drive to '0'
Bit 4	CPUCLK4 (Active/Inactive) (-31 ONLY) Not available on -21
Bit 3	CPUCLK3 (Active/Inactive)
Bit 2	CPUCLK2 (Active/Inactive)
Bit 1	CPUCLK1 (Active/Inactive)
Bit 0	CPUCLK0 (Active/Inactive)

Byte 3: SDRAM Active/Inactive Register
(1 = Active, 0 = Inactive), Default = Active

Bit	Description
Bit 7	SDRAM7 (Active/Inactive)
Bit 6	SDRAM6 (Active/Inactive)
Bit 5	SDRAM5 (Active/Inactive)
Bit 4	SDRAM4 (Active/Inactive)
Bit 3	SDRAM3 (Active/Inactive)
Bit 2	SDRAM2 (Active/Inactive)
Bit 1	SDRAM1 (Active/Inactive)
Bit 0	SDRAM0 (Active/Inactive)

Byte 5: Peripheral Active/Inactive Register
(1 = Active, 0 = Inactive), Default = Active

Bit	Description
Bit 7	(Reserved drive to '0')
Bit 6	(Reserved) drive to '0'
Bit 5	IOAPIC1 (Active/Inactive)
Bit 4	IOAPIC0 (Active/Inactive)
Bit 3	(Reserved) drive to '0'
Bit 2	(Reserved) drive to '0'
Bit 1	REF1 (Active/Inactive)(-31 ONLY)
Bit 0	REF0 (Active/Inactive)

Byte 2: PCI Active/Inactive Register
(1 = Active, 0 = Inactive), Default = Active

Bit	Description
Bit 7	(Reserved) drive to '0'
Bit 6	PCICLK6 (Active/Inactive)
Bit 5	PCICLK5 (Active/Inactive)
Bit 4	PCICLK4 (Active/Inactive)
Bit 3	PCICLK3 (Active/Inactive)
Bit 2	PCICLK2 (Active/Inactive)
Bit 1	PCICLK1 (Active/Inactive)
Bit 0	PCICLK0 (Active/Inactive)

Byte 4: SDRAM Active/Inactive Register
(1 = Active, 0 = Inactive), Default = Active

Bit	Description
Bit 7	SDRAM15 (Active/Inactive) (-21 ONLY) Not available on -31
Bit 6	SDRAM14 (Active/Inactive) (-21 ONLY) Not available on -31
Bit 5	SDRAM13 (Active/Inactive) (-21 ONLY) Not available on -31
Bit 4	SDRAM12 (Active/Inactive)
Bit 3	SDRAM11 (Active/Inactive)
Bit 2	SDRAM10 (Active/Inactive)
Bit 1	SDRAM9 (Active/Inactive)
Bit 0	SDRAM8 (Active/Inactive)

Byte 6: Reserved, for future use



Maximum Ratings

(Above which the useful life may be impaired. For user guidelines, not tested.)

Supply Voltage -0.5 to +7.0V
Input Voltage -0.5V to $V_{DD}+0.5$

Storage Temperature (Non-Condensing) ... -65°C to +150°C
Max. Soldering Temperature (10 sec) +260°C
Junction Temperature +150°C
Package Power Dissipation 1W
Static Discharge Voltage >2000V
(per MIL-STD-883, Method 3015, like V_{DD} pins tied together)

Operating Conditions^[3]

Parameter	Description	Min.	Max.	Unit
AV_{DD}, V_{DDQ3}	Analog and Digital Supply Voltage	3.135	3.465	V
V_{DDCPU}	CPU Supply Voltage	2.375	2.9	V
V_{DDQ2}	IOAPIC Supply Voltage	2.375	2.9	V
T_A	Operating Temperature, Ambient	0	70	°C
C_L	Max. Capacitive Load on CPUCLK, USBCLK, IOCLK, REF[1:2], IOAPIC[0:1] PCICLK, SDRAM REF0	10 30, 20 20	20 30 45	pF
$f_{(REF)}$	Reference Frequency, Oscillator Nominal Value	14.318	14.318	MHz

Electrical Characteristics Over the Operating Range

Parameter	Description	Test Conditions	Min.	Max.	Unit
V_{IH}	High-level Input Voltage	Except Crystal Inputs	2.0		V
V_{IL}	Low-level Input Voltage	Except Crystal Inputs		0.8	V
V_{ILiic}	Low-level Input Voltage	I ² C inputs only		0.7	V
V_{OH}	High-level Output Voltage ^[4]	$V_{DDCPU} = 2.375V, V_{DDQ2} = 2.375V$ $I_{OH} = 16\text{ mA}$ CPUCLK $I_{OH} = 18\text{ mA}$ IOAPIC	2.0		V
V_{OL}	Low-level Output Voltage ^[4]	$V_{DDCPU} = 2.375V, V_{DDQ2} = 2.375V$ $I_{OL} = 27\text{ mA}$ CPUCLK $I_{OL} = 29\text{ mA}$ IOAPIC		0.4	V
V_{OH}	High-level Output Voltage ^[4]	$V_{DDQ3}, AV_{DD}, V_{DDCPU} = 3.135V$ $I_{OH} = 36\text{ mA}$ SDRAM $I_{OH} = 32\text{ mA}$ PCICLK $I_{OH} = 36\text{ mA}$ REF0	2.4		V
V_{OL}	Low-level Output Voltage ^[4]	$V_{DDQ3}, AV_{DD}, V_{DDCPU} = 3.135V$ $I_{OL} = 29\text{ mA}$ SDRAM $I_{OL} = 26\text{ mA}$ PCICLK $I_{OL} = 29\text{ mA}$ REF0		0.4V	V
I_{IH}	Input High Current	$V_{IH} = V_{DD}$	-5	+5	μA
I_{IL}	Input Low Current	$V_{IL} = 0V$		5	μA
I_{OZ}	Output Leakage Current	Three-state	-10	+10	μA
I_{DD}	Power Supply Current ^[4]	$V_{DD} = 3.465V, V_{IN} = 0$ or V_{DD} , Loaded Outputs, CPU clocks = 66.67 MHz		310	mA
I_{DD}	Power Supply Current ^[4]	$V_{DD} = 3.465V, V_{IN} = 0$ or V_{DD} , Unloaded Outputs		130	mA

Notes:

- 3. Electrical parameters are guaranteed with these operating conditions.
- 4. Parameter guaranteed by design and characterization. Not 100% tested in production.

CY2276A-21 Switching Characteristics^[4,5] Over the Operating Range

Parameter	Output	Description	Test Conditions	Min.	Typ.	Max.	Unit
t ₁	CPUCLK, SDRAM, REF0, IOAPIC	Output Duty Cycle ^[6]	t ₁ = t _{1A} ÷ t _{1B}	45	50	55	%
t ₁	PCI	Output Duty Cycle ^[6]	t ₁ = t _{1A} ÷ t _{1B}	40	50	55	%
t _{1C}	CPUCLK	CPU Clock HIGH Time	Above 2.0V, 66.6 MHz, V _{DDCPU} = 2.5V	5.2			ns
t _{1C}	PCICLK	PCI Clock HIGH Time	Above 2.4V, 33.3 MHz, V _{DD} = 3.3V	12.0			ns
t _{1D}	CPUCLK	CPU Clock LOW Time	Below 0.4V, 66.6 MHz, V _{DDCPU} = 2.5V	5.0			ns
t _{1D}	PCICLK	PCI Clock LOW Time	Below 0.4V, 33.3 MHz, V _{DD} = 3.3V	12.0			ns
t ₂	CPUCLK	CPU Clock Rising and Falling Edge Rate	Between 0.4V and 2.0V	0.9		4.0	V/ns
t ₂	PCICLK	PCI Clock Rising and Falling Edge Rate	Between 0.4V and 2.4V	1.0		4.0	V/ns
t ₂	SDRAM	SDRAM Rising and Falling Edge Rate	Between 0.4V and 2.4V	0.9		4.0	V/ns
t ₂	REF0	REF0 Rising and Falling Edge Rate	Between 0.4V and 2.4V	0.75		4.0	V/ns
t ₂	IOAPIC	IOAPIC Rising and Falling Edge Rate	Between 0.4V and 2.0V	0.75		4.0	V/ns
t ₃	CPUCLK	CPU Clock Rise Time	Between 0.4V and 2.0V, V _{DDCPU} = 2.5V	0.4		1.78	ns
t ₄	CPUCLK	CPU Clock Fall Time	Between 2.0V and 0.4V, V _{DDCPU} = 2.5V	0.4		1.78	ns
t ₅	CPUCLK	CPU-CPU Clock Skew	Measured at 1.25V, V _{DDCPU} = 2.5V		100	250	ps
t ₆	CPUCLK, PCICLK	CPU-PCI Clock Skew	Measured at 1.25V for CPU clocks and 1.5V for other clocks, V _{DDCPU} = 2.5V, V _{DD} = 3.3V	1.0	3.0	6.0	ns
t ₇	CPUCLK, SDRAM	CPU-SDRAM Clock Skew	Measured at 1.25V for CPU clocks and 1.5V for other clocks, V _{DDCPU} = 2.5V, V _{DD} = 3.3V			650	ps
t ₈	CPUCLK	Cycle-Cycle Clock Jitter	Measured at 1.25V, V _{DDCPU} = 2.5V			400	ps
t ₈	PCICLK SDRAM	Cycle-Cycle Clock Jitter	Measured at 1.5V, V _{DD} = 3.3V			500	ps
t ₉	CPUCLK, PCICLK, SDRAM	Power-up Time	CPU, PCI, and SDRAM clock stabilization from power-up			3	ms

Notes:

5. All parameters specified with loaded outputs.
6. Duty cycle is measured at 1.5V when V_{DD} = 3.3V. When V_{DDCPU} = 2.5V, CPUCLK duty cycle is measured at 1.25V.

CY2276A-31 Switching Characteristics^[4,5] Over the Operating Range

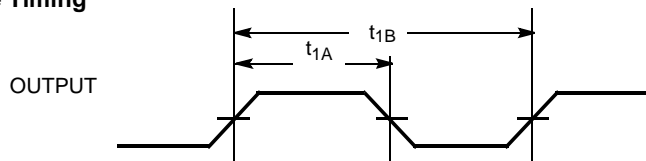
Parameter	Output	Description	Test Conditions	Min.	Typ.	Max.	Unit
t ₁	CPUCLK, SDRAM, REF0, IOAPIC	Output Duty Cycle ^[6]	t ₁ = t _{1A} ÷ t _{1B}	45	50	55	%
t ₁	PCI	Output Duty Cycle ^[6]	t ₁ = t _{1A} ÷ t _{1B}	40	50	55	%
t _{1C}	CPUCLK	CPU Clock HIGH Time	Above 2.0V, 66.6 MHz, V _{DDCPU} = 2.5V	5.2			ns
t _{1C}	PCICLK	PCI Clock HIGH Time	Above 2.4V, 33.3 MHz, V _{DD} = 3.3V	12.0			ns
t _{1D}	CPUCLK	CPU Clock LOW Time	Below 0.4V, 66.6 MHz, V _{DDCPU} = 2.5V	5.0			ns
t _{1D}	PCICLK	PCI Clock LOW Time	Below 0.4V, 33.3 MHz, V _{DD} = 3.3V	12.0			ns
t ₂	CPUCLK	CPU Clock Rising and Falling Edge Rate	Between 0.4V and 2.0V	0.75		4.0	V/ns
t ₂	PCICLK	PCI Clock Rising and Falling Edge Rate	Between 0.4V and 2.4V	0.75		4.0	V/ns
t ₂	SDRAM	SDRAM Rising and Falling Edge Rate	Between 0.4V and 2.4V	0.75		4.0	V/ns
t ₂	REF0	REF0 Rising and Falling Edge Rate	Between 0.4V and 2.4V	0.75		4.0	V/ns
t ₂	IOAPIC	IOAPIC Rising and Falling Edge Rate	Between 0.4V and 2.0V	0.75		4.0	V/ns
t ₃	CPUCLK	CPU Clock Rise Time	Between 0.4V and 2.0V, V _{DDCPU} = 2.5V	0.4		2.13	ns
t ₄	CPUCLK	CPU Clock Fall Time	Between 2.0V and 0.4V, V _{DDCPU} = 2.5V	0.4		2.13	ns
t ₅	CPUCLK	CPU-CPU Clock Skew	Measured at 1.25V, V _{DDCPU} = 2.5V		100	250	ps
t ₆	CPUCLK, PCICLK	CPU-PCI Clock Skew	Measured at 1.25V for CPU clocks and 1.5V for other clocks, V _{DDCPU} = 2.5V, V _{DD} = 3.3V	1.0	3.0	5.0	ns
t ₇	CPUCLK, SDRAM	CPU-SDRAM Clock Skew	Measured at 1.25V for CPU clocks and 1.5V for other clocks, V _{DDCPU} = 2.5V, V _{DD} = 3.3V			650	ps
t ₈	CPUCLK	Cycle-Cycle Clock Jitter	Measured at 1.25V, V _{DDCPU} = 2.5V			500	ps
t ₈	PCICLK, SDRAM	Cycle-Cycle Clock Jitter	Measured at 1.5V, V _{DD} = 3.3V			550	ps
t ₉	CPUCLK, PCICLK, SDRAM	Power-up Time	CPU, PCI, and SDRAM clock stabilization from power-up			3	ms

Timing Requirement for the I²C Bus

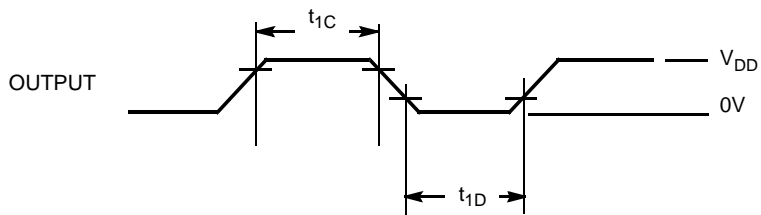
Parameter	Description	Min.	Max.	Unit
t ₁₀	SCLK Clock Frequency	0	100	kHz
t ₁₁	Time the bus must be free before a new transmission can start	4.7		μs
t ₁₂	Hold time start condition. After this period the first clock pulse is generated.	4		μs
t ₁₃	The Low period of the clock	4.7		μs
t ₁₄	The High period of the clock	4		μs
t ₁₅	Setup time for start condition. (Only relevant for a repeated start condition.)	4.7		μs
t ₁₆	Hold time DATA for CBUS compatible masters for I ² C devices	5 0		μs
t ₁₇	DATA input set-up time	250		ns
t ₁₈	Rise time of both SDATA and SCLK inputs		1	μs
t ₁₉	Fall time of both SDATA and SCLK inputs		300	ns
t ₂₀	Set-up time for stop condition	4.0		μs

Switching Waveforms

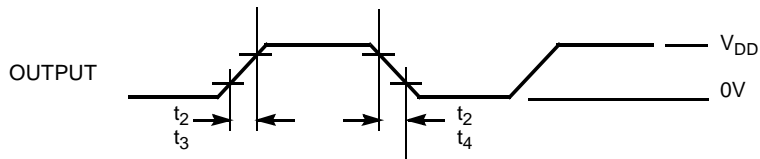
Duty Cycle Timing



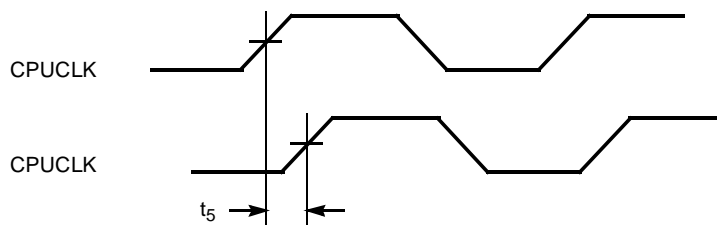
CPUCLK Outputs HIGH/LOW Time



All Outputs Rise/Fall Time

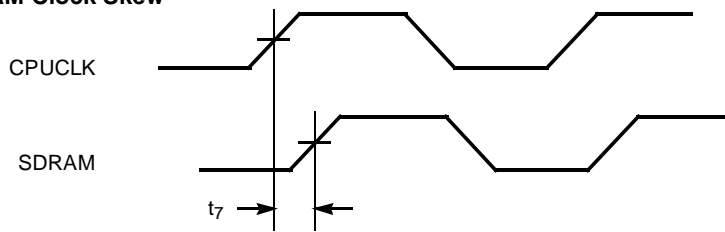


CPU-CPU Clock Skew

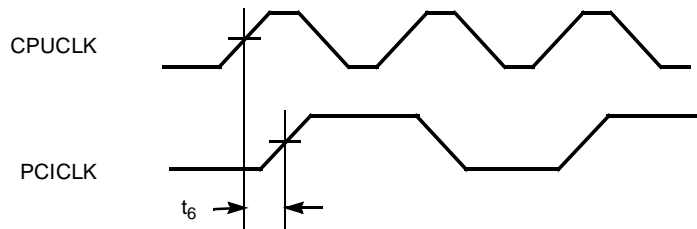


Switching Waveforms (continued)

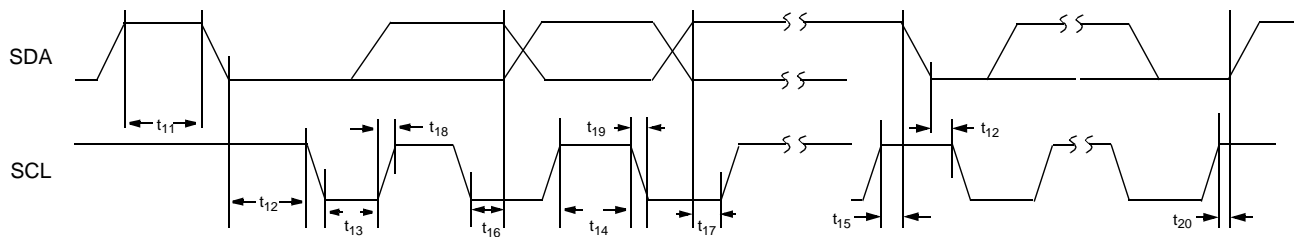
CPU-SDRAM Clock Skew



CPU-PCI Clock Skew



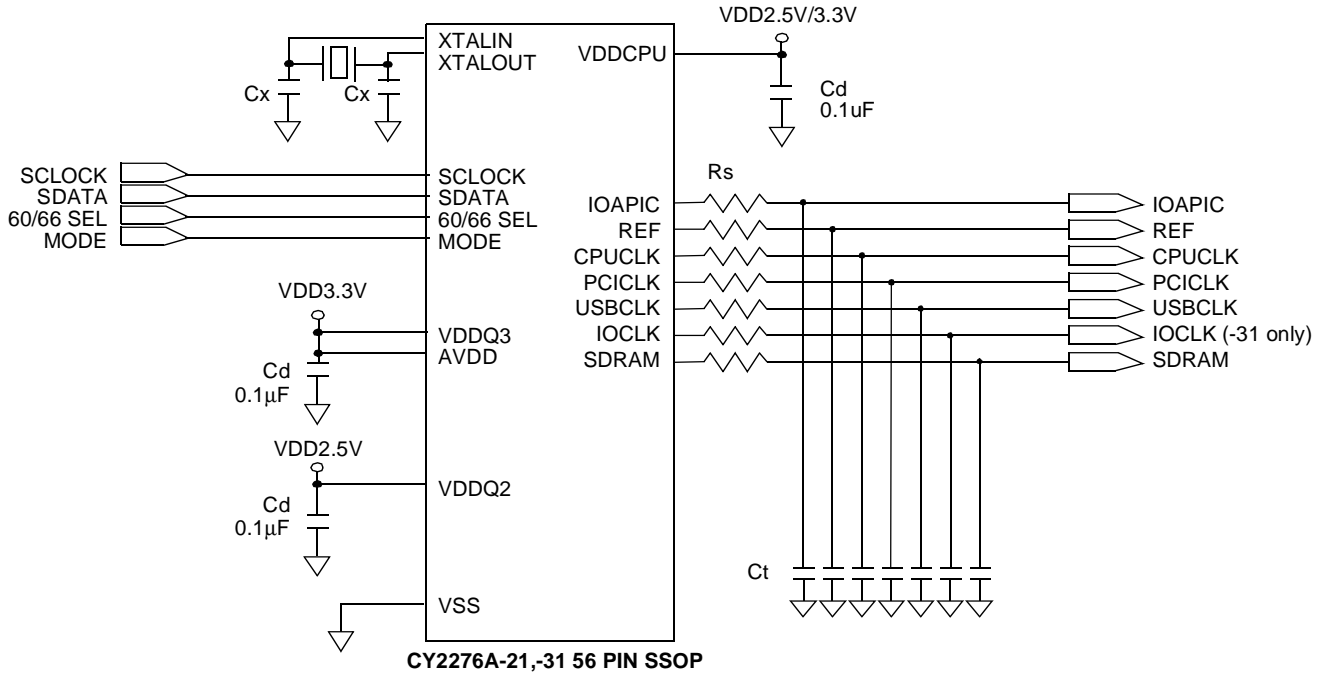
Timing Requirements for the I²C Bus



Application Information

Clock traces must be terminated with either series or parallel termination, as they are normally done.

Application Circuit

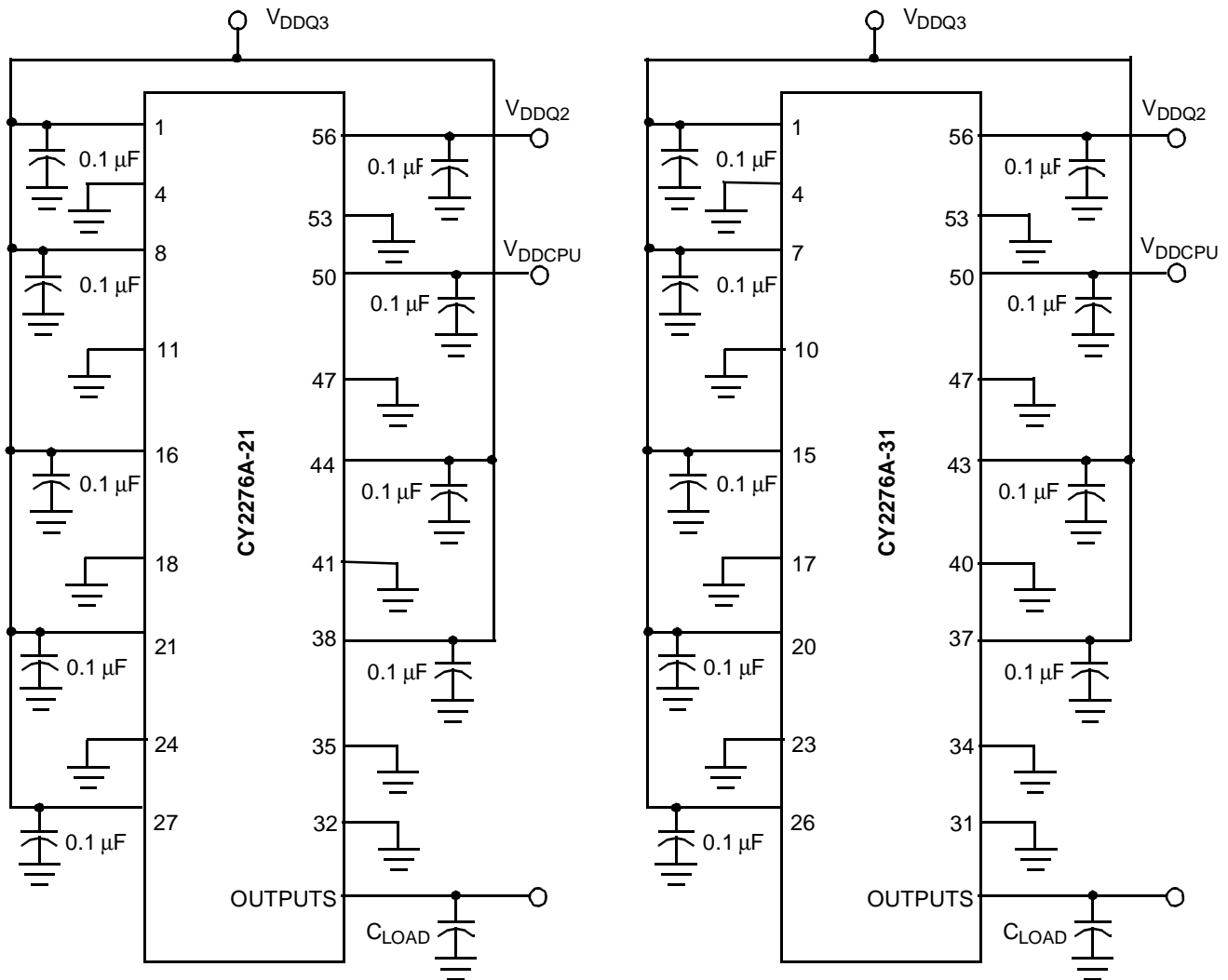


Cd = DECOUPLING CAPACITORS
 Ct = OPTIONAL EMI-REDUCING CAPACITORS
 Cx = OPTIONAL LOAD MATCHING CAPACITOR
 Rs = SERIES TERMINATING RESISTORS

Summary

- A parallel-resonant crystal should be used as the reference to the clock generator. The operating frequency and C_{LOAD} of this crystal should be as specified in the data sheet. Optional trimming capacitors may be needed if a crystal with a different C_{LOAD} is used. Footprints must be laid out for flexibility.
- Surface mount, low-ESR, ceramic capacitors should be used for filtering. Typically, these capacitors have a value of 0.1 μF . In some cases, smaller value capacitors may be required.
- The value of the series terminating resistor satisfies the following equation, where R_{trace} is the loaded characteristic impedance of the trace, R_{out} is the output impedance of the clock generator (specified in the data sheet), and R_{series} is the series terminating resistor.

$$R_{series} \geq R_{trace} - R_{out}$$
- Footprints must be laid out for optional EMI-reducing capacitors, which should be placed as close to the terminating resistor as is physically possible. Typical values of these capacitors range from 4.7 pF to 22 pF.
- A Ferrite Bead **may** be used to isolate the Board V_{DD} from the clock generator V_{DD} island. Ensure that the Ferrite Bead offers greater than 50 Ω impedance at the clock frequency, under loaded DC conditions. Please refer to the application note "Layout and Termination Techniques for Cypress Clock Generators" for more details.
- If a Ferrite Bead is used, a 10 μF – 22 μF tantalum bypass capacitor should be placed close to the Ferrite Bead. This capacitor prevents power supply droop during current surges.

Test Circuit


Note: All Capacitors must be placed as close to the pins as is physically possible

Ordering Information

Ordering Code	Package Name	Package Type	Operating Range
CY2276APVC-21	O56	56-Pin SSOP	Commercial
CY2276APVC-31	O56	56-Pin SSOP	Commercial

Document #: 38-00611-D

Package Diagram

56-Lead Shrunken Small Outline Package O56

